

T-52-13-90

Latch-Immune High-Speed, High-Current Single MOSFET/IGBT Driver IXLD4420/4429

General Description

The IXLD4420/4429 MOSFET/IGBT Drivers are tough, efficient, and easy to use. This family of devices are 6A (peak) single output MOSFET or IGBT Drivers.

The IXLD4420/4429 will drive even the largest MOSFETs and IGBTs at high speed improving the safe operating area margins.

These devices are tough due to extra steps taken to protect them from failures. An epitaxial layer is used to prevent CMOS Latch-up. Proprietary circuits allow the input to swing negative as much as 5V without damaging the part. Special circuits have been added to protect against damage from Electro-static Discharge. A special molding compound is used for increased moisture resistance and increased ability to withstand high voltages.

Because these devices are fabricated in CMOS, they run cool, use less power and are easier to drive. The rail-to-rail swing capability of CMOS better insures adequate gate voltage to the MOSFET/IGBT during turn on and turn off.

The MOSFET/IGBT Drivers are flexible and easy to use. These devices replace three or more discrete components with a single device to save PCB area. Any logic input from 2.4V to V_S can be used without the need for external speed-up capacitors or resistor networks.

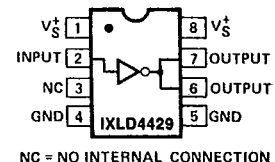
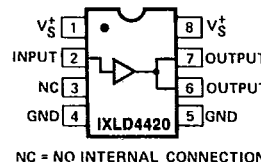
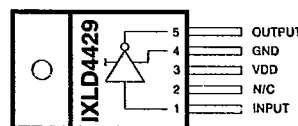
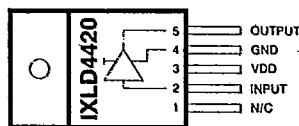
This family of devices is available in inverting (IXLD4429) and non-inverting (IXLD4420) configurations. There is an IXYS MOSFET/IGBT Driver just right for any application.

Features

- Latch-Up Protected. Will Withstand 500mA Reverse Output Current
- Logic Input Will Withstand Negative Swing of Up to 5V
- Matched Rise and Fall Times 25nS
- High Peak Output Current 6.0 Amp Peak
- High Capacitive Load Drive Capability 10,000pF in 60nS
- Wide Operating Range 4.5V to 18V
- Low Delay Time 55nS Max.
 - Rise Time, Typical 20nS
 - Fall Time, Typical 20nS
- Consistent Delay Times with Changes in Supply Voltage
- Logic High Input for any Voltage From 2.4V to V_S
- Logic Input Threshold Independent of Supply Voltage
- Low Supply Current
 - 450 μ A with Logic 1 Input
 - 55 μ A with Logic 0 Input
- Low Output Impedance 2.5 Ohms
- Output Voltage Swing to Within 25mV of Ground or V_S +
- Available in Inverting (IXLD4429) and Non-Inverting (IXLD4420) Configurations

The IXLD4429 is pin-compatible with the popular IXLD429. The TO-220 packaged version allows the user to utilize the driver at higher frequencies without the power dissipation limit of the DIP package.

Pin Configuration



NC = NO INTERNAL CONNECTION

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Applications

- Switch Mode Power Supplies
- Motor Controls
- Pulse Transformer Drive
- Class D Switching Amplifiers

Ordering Information

Part No.	Package	Temperature Range
IXLD4420/29COA	8-Pin SO	0°C to 70°C
IXLD4420/29CPA	8-Pin Plastic DIP	0°C to 70°C
IXLD4420/29IJA*	8-Pin CerDIP	-25°C to 85°C
IXLD4420/29MJA**	8-Pin CerDIP	-55°C to 125°C
IXLD4420/29Y	CHIP	25°C
IXLD4420/29CTA	TO-220 (5 lead)	0°C to 70°C

* For devices with 125°C, 160 Hour Burn In add /BI to part number suffix.

** 883 processing available.

High-Speed, High-Current Single MOSFET/IGBT Driver

IXLD4420/4429

Absolute Maximum Ratings (Notes 1, 2, 3)

Power Dissipation

Plastic	500mW
CerDIP	800mW
TO-220	16W

Derating Factors

Plastic	5.6mW/°C Above 36°C
CerDIP	6.0mW/°C
TO-220	130mW/°C

Supply Voltage 20V

Input Voltage Any Terminal -5V to $V_S + 0.3V$

Operating Temperature

M Version	-55°C to +125°C
I Version	-25°C to +85°C
C Version	0°C to +70°C
Maximum Junction Temperature	+150°C
Storage Temperature	-55°C to +150°C
Lead Temperature (10 Sec)	300°C
CerDIP θ_{JA} (Junction - Ambient)	150°C/W
Plastic θ_{JA} (Junction - Ambient)	170°C/W
TO-220 θ_{JA} (Junction - Ambient)	80°C/W
TO-220 θ_{JC} (Junction - Case)	7.5°C/W

IXLD4420/4429

Electrical Characteristics: $T_A = 25^\circ\text{C}$ with $4.5V \leq V_S \leq 18V$ unless otherwise specified.

TYPE	SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
INPUT	V_{IH}	Logic 1 Input Voltage		2.4	1.8	—	V
	V_{IL}	Logic 0 Input Voltage		—	1.3	0.8	V
	V_{IN} (Max)	Input Voltage Range		-5.0	—	$V_S + 0.3$	V
Note 2	I_{IN}	Input Current	$0V \leq V_{IN} \leq V_S$	-10	—	10	μA
OUTPUT	V_{OH}	High Output Voltage	See Figure 1	$V_S - 0.025$	—	—	V
	V_{OL}	Low Output Voltage	See Figure 1	—	—	0.025	V
	R_O	Output Resistance	$V_{IN} = 0.8V$ for 4420; $V_{IN} = 2.4V$ for 4429 $I_{OUT} = 10\text{mA}$, $V_S = 18V$	—	2.1	2.8	Ω
	R_O	Output Resistance	$V_{IN} = 2.4V$ for 4420; $V_{IN} = 0.8V$ for 4429 $I_{OUT} = 10\text{mA}$, $V_S = 18V$	—	1.5	2.5	Ω
	I_{PK}	Peak Output Current	$V_S = 18V$ (See Figure 5)	—	6.0	—	A
	I	Latch-Up Protection	Withstand Reverse Current	>500	—	—	mA
SWITCHING	T_R	Rise Time	Test Figure 1, $C_L = 2500\text{pF}$	—	25	35	nS
	T_F	Fall Time	Test Figure 1, $C_L = 2500\text{pF}$	—	25	35	nS
	T_{D1}	Delay Time	Test Figure 1	—	55	75	nS
	T_{D2}	Delay Time	Test Figure 1	—	55	75	nS
Note 3	I_S	Power Supply Current	$V_{IN} = 3.0V$	—	0.45	1.5	mA
SUPPLY	I_S	Power Supply Current	$V_{IN} = 0.0V$	—	55	150	μA
	V_S	Operating Supply Voltage		4.5	—	18	V

NOTES:

- Functional operation above maximum stress ratings is not implied.
- Static Sensitive Device. Store only in conductive

- containers. Handling personnel and equipment should be grounded to prevent damage from static discharge.
- Switching times guaranteed by design.

IXLD4420/4429

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Electrical Characteristics: Over operating temperature range with $4.5V \leq V_S \leq 18V$ unless otherwise specified.

TYPE	SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
INPUT	V_{IH}	Logic 1 Input Voltage		2.4	—	—	V
	V_{IL}	Logic 0 Input Voltage		—	—	0.8	V
	V_{IN} (Max)	Input Voltage Range		-5.0	—	$V'_S + 0.3$	V
	I_{IN}	Input Current	$0V \leq V_{IN} \leq V_S$	-10	—	10	μA
OUTPUT	V_{OH}	High Output Voltage	See Figure 1	$V'_S - 0.025$	—	—	V
	V_{OL}	Low Output Voltage	See Figure 1	—	—	0.025	V
	R_O	Output Resistance	$V_{IN} = 0.8V$ for 4420; $V_{IN} = 2.4V$ for 4429 $I_{OUT} = 10mA$, $V_S = 18V$	—	3.0	5.0	Ω
	R_O	Output Resistance	$V_{IN} = 2.4V$ for 4420; $V_{IN} = 0.8V$ for 4429 $I_{OUT} = 10mA$, $V_S = 18V$	—	2.3	5.0	Ω
SWITCHING	T_R	Rise Time	Test Figure 1, $C_L = 2500pF$	—	32	60	nS
	T_F	Fall Time	Test Figure 1, $C_L = 2500pF$	—	34	60	nS
	T_{D1}	Delay Time	Test Figure 1	—	50	100	nS
	T_{D2}	Delay Time	Test Figure 1	—	65	100	nS
SUPPLY	I_S	Power Supply Current	$V_{IN} = 3.0V$	—	.45	3.0	mA
	I_S	Power Supply Current	$V_{IN} = 0.0V$	—	.06	0.4	mA
	V'_S	Operating Supply Voltage		4.5	—	18	V

NOTES:

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Figure 1. Functional Diagram

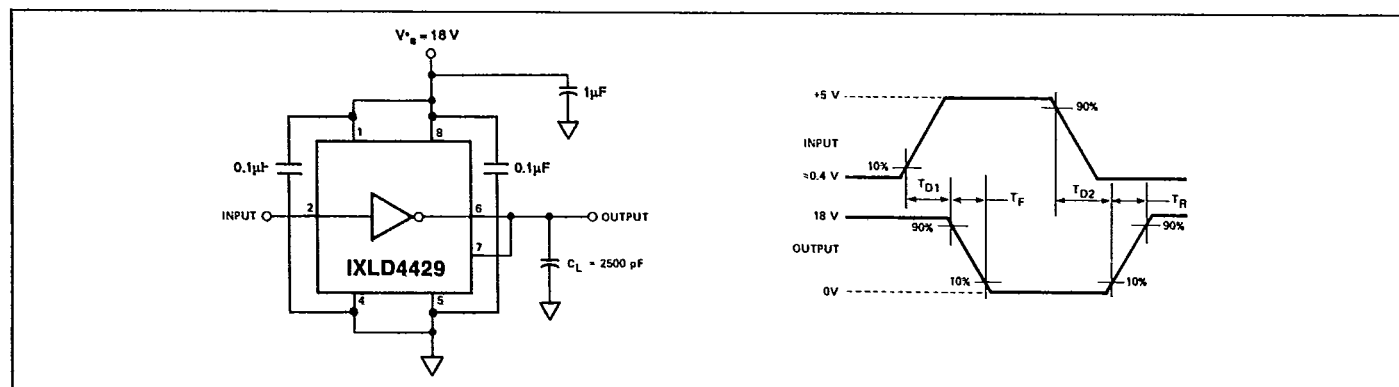
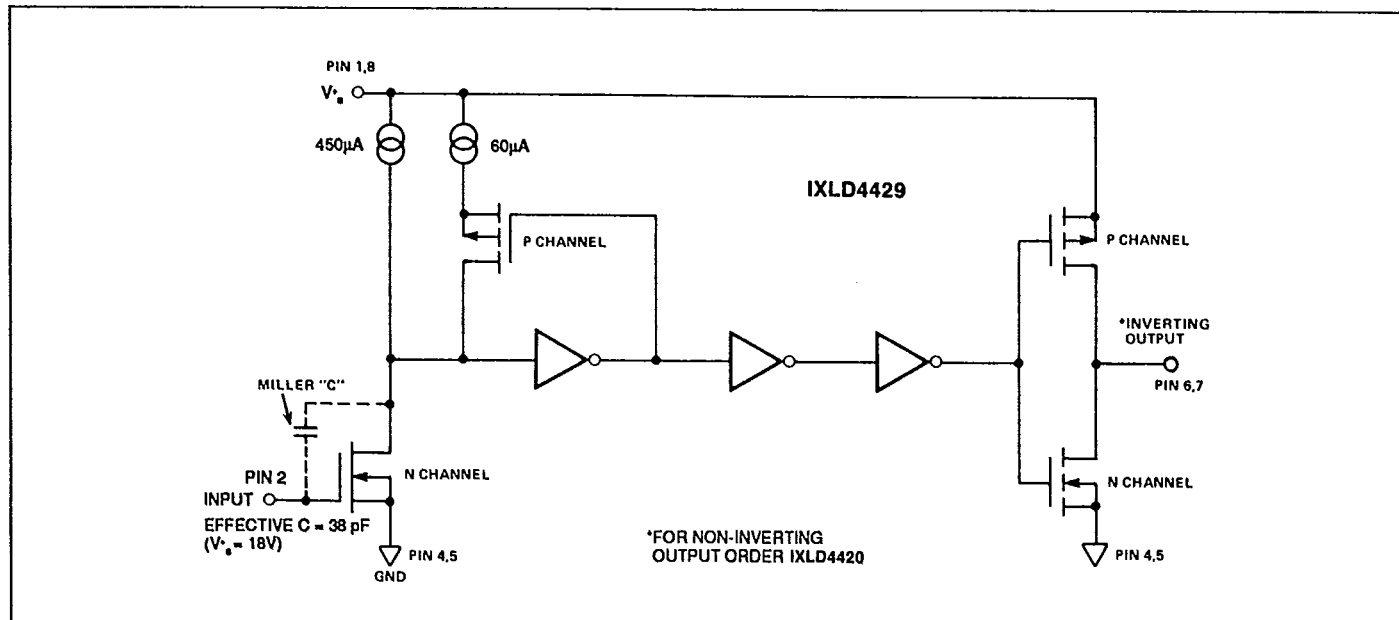


Figure 2. Switching Time Test Circuit

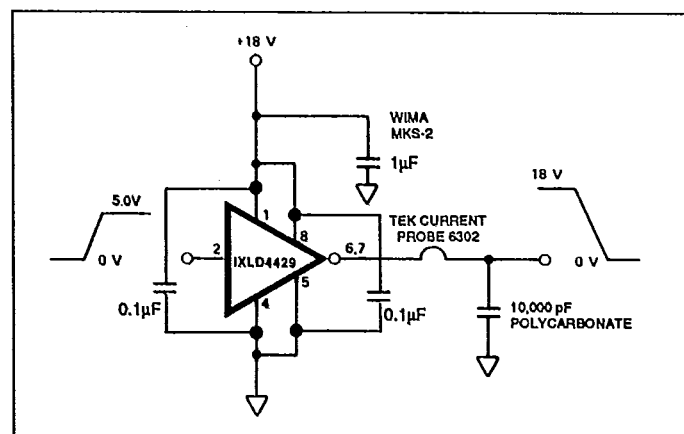
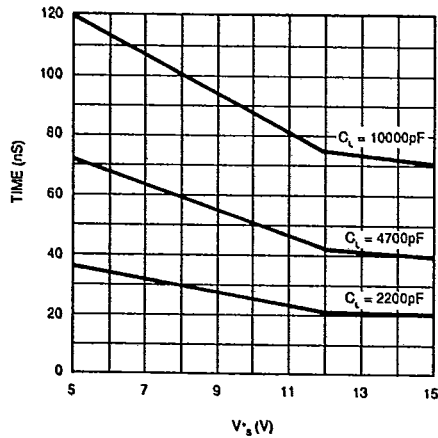


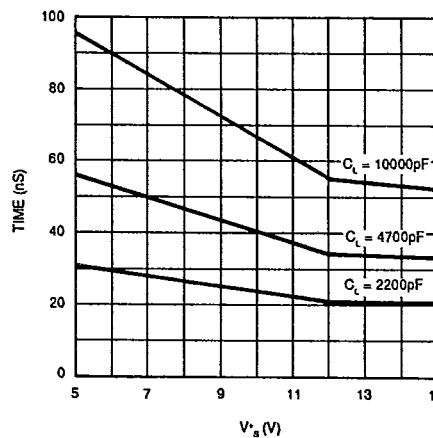
Figure 3. Peak Output Current Test Circuit

Typical Characteristics Curves

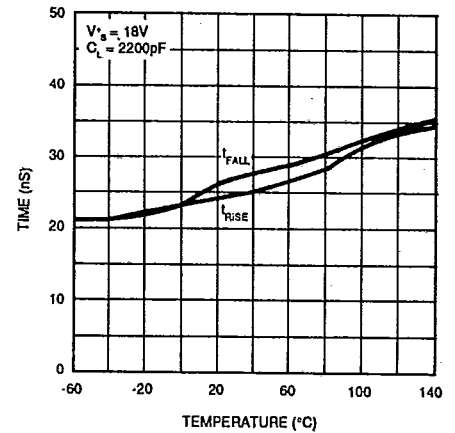
Rise Time vs Supply Voltage



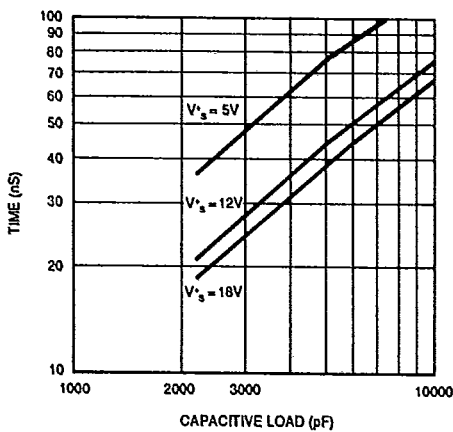
Fall Time vs Supply Voltage



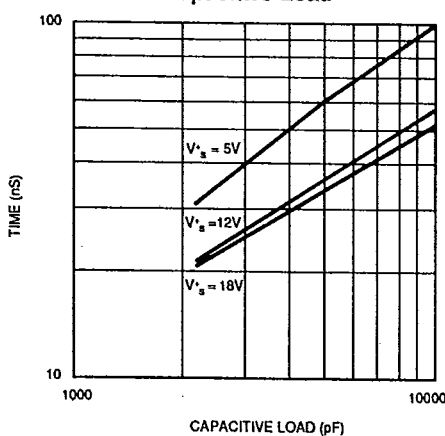
Rise and Fall Time vs Temperature



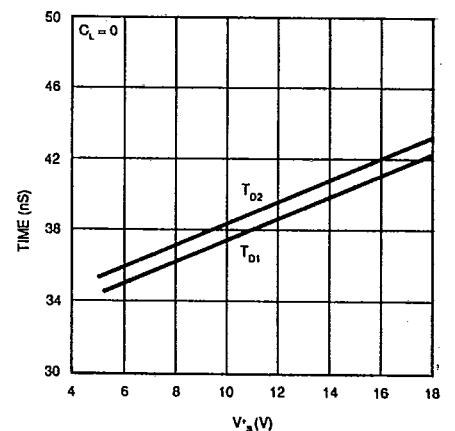
Rise Time vs Capacitive Load



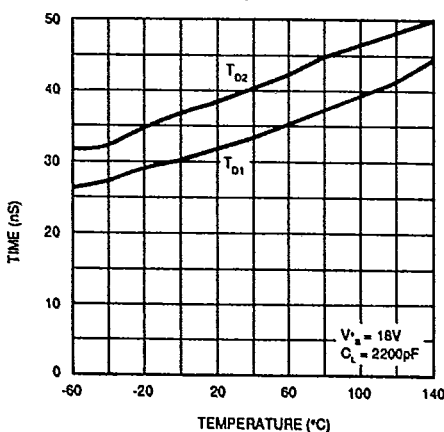
Fall Time vs Capacitive Load



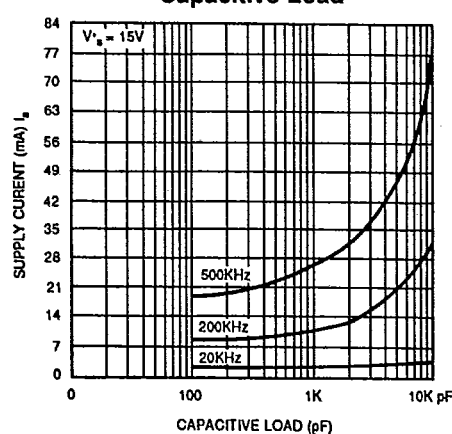
Propagation Delay Time vs Supply Voltage



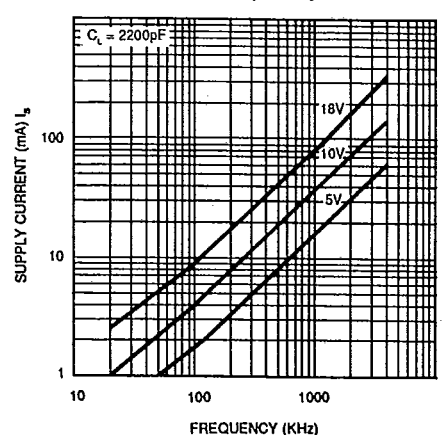
Propagation Delay Time vs Temperature



Supply Current vs Capacitive Load



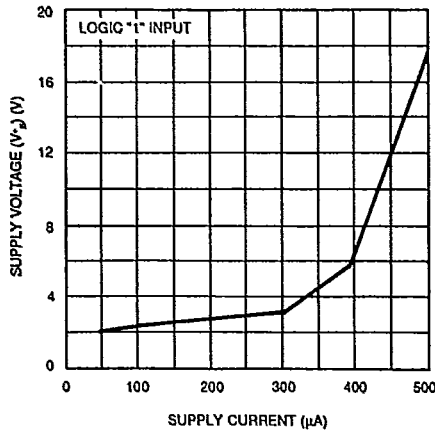
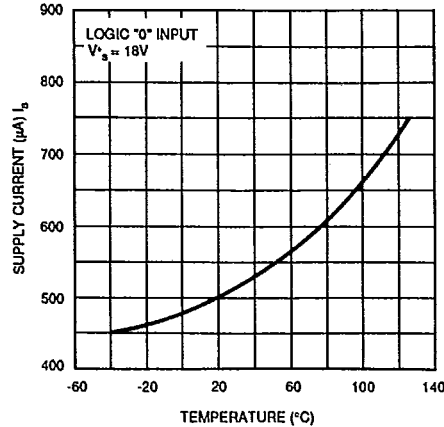
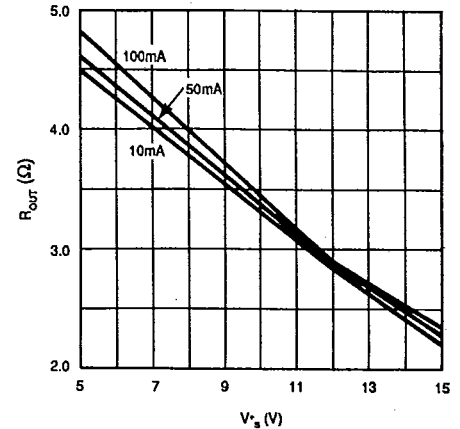
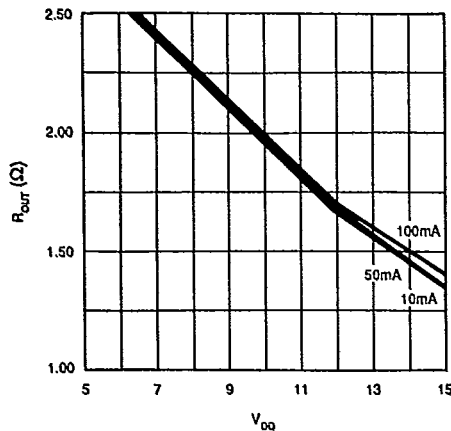
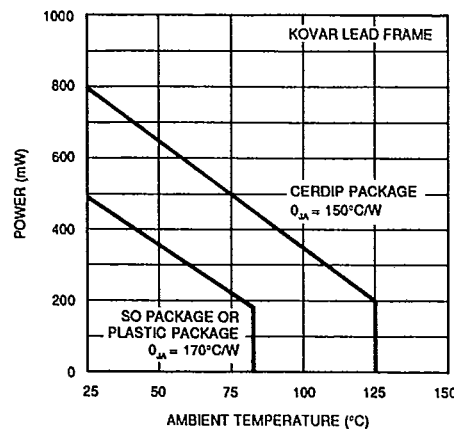
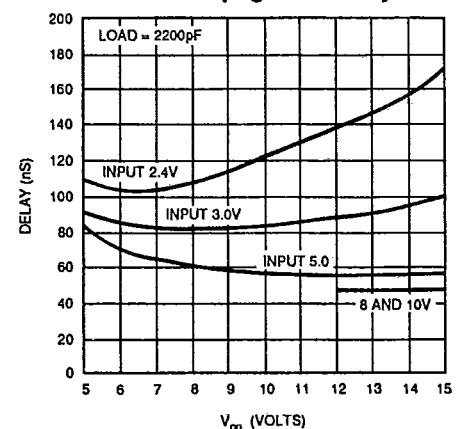
Supply Current vs Frequency



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Typical Characteristics Curves (Cont.)

Quiescent Power Supply
Current vs Supply VoltageQuiescent Power Supply
Current vs TemperatureHigh State
Output ResistanceLow State
Output ResistancePackage Power
DissipationEffect of Input Amplitude
on Propagation Delay

Notes:

1. Derate Plastic 5.88mW/°C
2. Derate CerDIP 6.67mW/°C

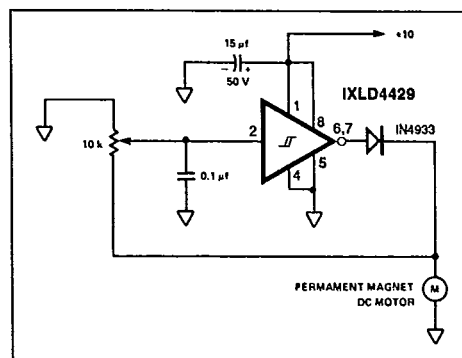


Figure 4. Motor Speed Controller

High-Speed, High-Current Single MOSFET/IGBT Driver

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Typical Applications

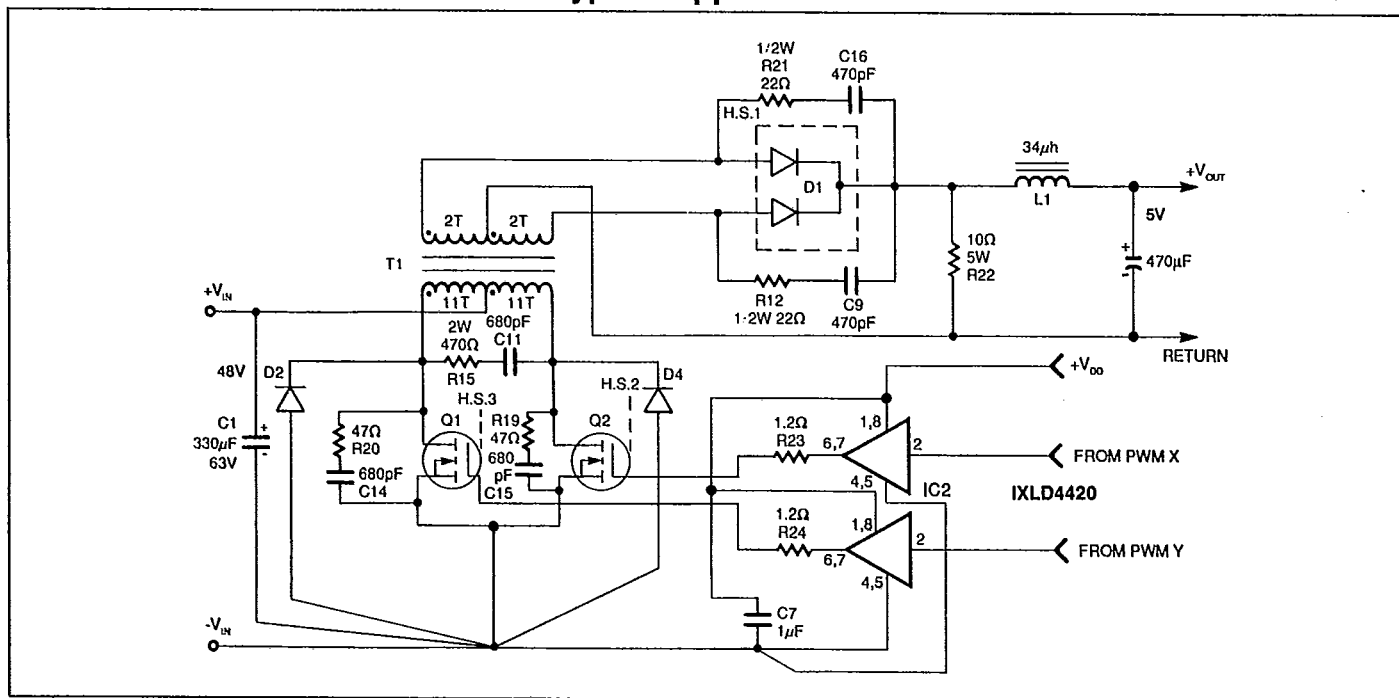


Figure 5. Push-Pull Power Stage

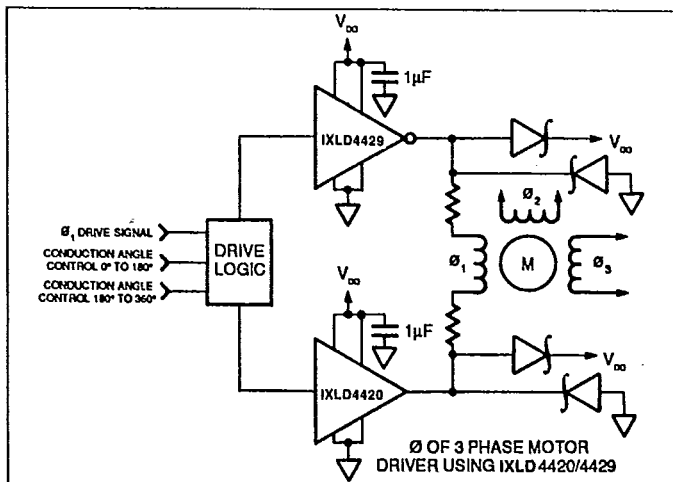


Figure 6. Direct Motor Drive

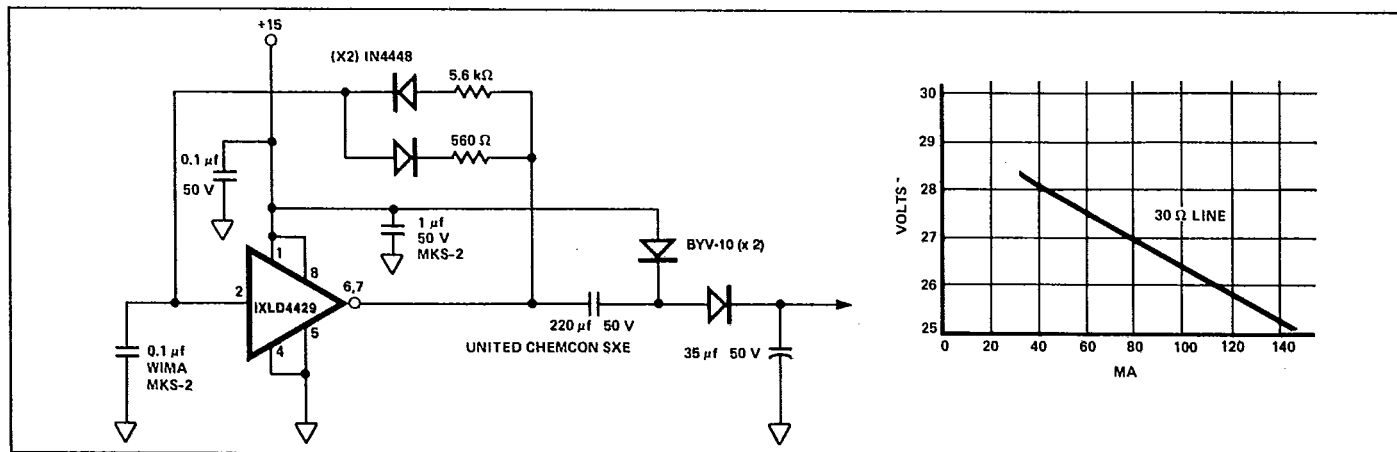


Figure 7. Self-Contained Voltage Doubler

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Supply Bypassing

Charging and discharging large capacitive loads quickly requires large currents. For example, charging a 2500pF load 18 volts in 25nS requires a 1.8A current from the device power supply.

The IXLD4420/4429 has double bonding on the supply pins, the ground pins and output pins. This serves to reduce parasitic lead inductance. Low inductance enables large drive currents to be switched very fast. It also reduces internal ringing that can cause voltage breakdown when the driver is operated at or near the maximum rated voltage.

Internal ringing can also cause output oscillation due to feedback. This feedback is added to the input signal since it is referenced to the same ground.

To guarantee low supply impedance over a wide frequency range, a parallel capacitor combination is recommended for supply bypassing. Low inductance ceramic disk capacitors with short lead lengths (<0.5 inch) should be used. A 1μF low ESR film capacitor in parallel with two .1μF low ESR ceramic capacitors, (such as AVX RAM GUARD®), provides adequate bypassing. Connect one ceramic capacitor directly between pins 1 and 4. Connect the second ceramic capacitor directly between pins 8 and 5.

Grounding

The high current capability of the IXLD4420/4429 demands careful PC board layout for best performance. Since the IXLD4429 is an inverting driver, any ground lead impedance will appear as negative feedback which can degrade switching speed. The feedback is especially noticeable with slow-rise time inputs. The IXLD4429 input structure includes about 300mV of hysteresis to ensure clean transitions and freedom from oscillation, but attention to layout is still recommended.

Figure 8 shows the feedback effect in detail. As the IXLD4429 input begins to go positive, the output goes negative and several amperes of current flow in the ground lead. As little as 0.05Ω of PC trace resistance can produce hundreds of millivolts at the IXLD4429 ground pins. If the driving logic is referenced to power ground, the effective logic input level is reduced and oscillation may result.

To ensure optimum performance, separate ground traces should be provided for the logic and power connections. Connecting the logic ground directly to the IXLD4429 GND pins will ensure full logic drive to the input and ensure fast output switching. Both of the IXLD4429 GND pins should still be connected to power ground.

Input Stage

The input voltage level of the IXLD4429 changes the quiescent supply current. The N-channel MOSFET input stage transistor drives a 450μA current source load. With a logic "1" input, the maximum quiescent supply current is 450μA. Logic "0" input level signals reduce quiescent current to 55μA maximum.

The IXLD4420/4429 input is designed to provide 300mV of hysteresis. This provides clean transitions, reduces noise sensitivity, and minimizes output stage current spiking when changing states. Input voltage threshold levels are approximately 1.5V, making the device TTL compatible over the 4.5V to 18V operating supply range. Input current is less than 10μA over this range.

The IXLD4429 can be directly driven by the TL494, SG1526/1527, SG1524, TSC170, TSC38C42 and similar switch mode power supply integrated circuits. By offloading the power-driving duties to the IXLD4420/4429, the power supply controller can operate at lower dissipation. This can improve performance and reliability.

The input can be greater than the V_S supply, however, current will flow into the input lead. The propagation delay for T_{PD2} will increase to as much as 400nS at room temperature. The input currents can be as high as 30mA p-p (6.4 mA rms) with the input being 6V greater than the supply voltage. No damage will occur to the IXLD4420/4429 however, and it will not latch.

The input appears as a 38pF capacitance, and does not change even if the input is driven from an A.C. source. Care should be taken so that the input does not go more than 5 volts below the negative rail.

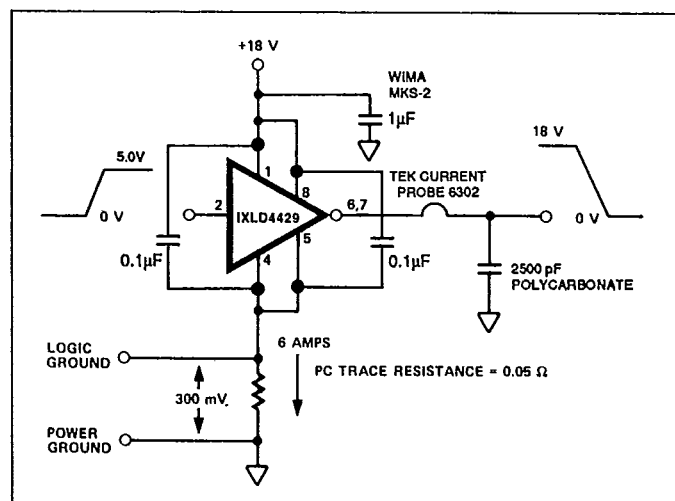


Figure 8: Switching Time Degradation Due to Negative Feedback

High-Speed, High-Current Single MOSFET/IGBT Driver

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Power Dissipation

CMOS circuits usually permit the user to ignore power dissipation. Logic families such as 4000 and 74C have outputs which can only supply a few milliamperes of current, and even shorting outputs to ground will not force enough current to destroy the device. The IXLD4420/4429 on the other hand, can source or sink several amperes and drive large capacitive loads at high frequency. The package power dissipation limit can easily be exceeded. Therefore, some attention should be given to power dissipation when driving low impedance loads and/or operating at high frequency. The TO-220 packaged device, with its higher power dissipation capability, permits driving low impedance loads at much higher frequency.

The supply current vs frequency and supply current vs capacitive load characteristics curves will aid in determining power dissipation calculations. Table 1 lists the maximum operating frequency for several power supply voltages when driving a 2500pF load. More accurate power dissipation figures can be obtained by adding the three dissipation sources.

Input signal duty cycle, power supply voltage, and capacitive load influence device power dissipation. Given power dissipation and package thermal resistance the maximum ambient operation temperature is easily calculated. The CerDIP 8-pin package junction to ambient thermal resistance is 150°C/W. At 25°C, the package is rated at 800mW maximum dissipation. Maximum allowable chip temperature is 150°C.

Three components make up total package power dissipation:

- Capacitive load dissipation (P_C)
- Quiescent power (P_Q)
- Transition power (P_T)

The capacitive load caused dissipation is a direct function of frequency, capacitive load, and supply voltage. The package power dissipation is:

$$\text{EQ.1: } P_C = fCV_S^2$$

where: f = switching frequency
 C = capacitive load
 V_S = supply voltage

Quiescent power dissipation depends on input signal duty cycle. A logic low input results in a low power dissipation mode with only .40mA total current drain. Logic high signals raise the current to 1.5mA maximum at 25°C or 3mA at high ambient temperature.

$$\text{EQ.2: } P_Q = V_S (D(I_H) + (1-D) I_L)$$

where: I_H = quiescent current with input high (3mA Max)
 I_L = quiescent current with input low (0.40mA Max)
 D = duty cycle (% of time input is high)

Transition power dissipation arises because the output stage N- and P-channel MOS transistors are "on" simultaneously for a very short period when the output changes. The transition package power dissipation is approximately:

$$\text{EQ.3: } P_T = fV_S^2 (A \cdot S \text{ rating from Figure 9})$$

An example shows the relative magnitude for each term.

Example 1:

$$\begin{aligned} C &= 2500\text{pF} \\ V_S &= 15\text{V} \\ D &= 50\% \\ f &= 200\text{kHz} \\ P_D &= \text{package power dissipation} = P_C + P_T + P_Q \\ &= 112\text{mW} + 103\text{mW} + 26\text{mW} \\ &= 241\text{mW} \\ T_J &= T_A + \theta_{JA} \times P_D \\ &= 25^\circ\text{C} + 150 \times .241 = 61.22^\circ\text{C} \end{aligned}$$

where: T_J = Junction temperature (150°C Max)

T_A = Ambient temperature

θ_{JA} = Junction to ambient thermal resistance (150°C/W, CerDIP)

NOTE: Ambient operating temperature should not exceed 85°C for "IJA" device or 125°C for "MJA" device.

Table 1: IXLD4429 Maximum Operating Frequency

V_S	Max Frequency
18V	500kHz
15V	700kHz
10V	1.6MHz
5V	6.5MHz

Conditions: 1. CerDIP Package ($\theta_{JA} = 150^\circ\text{C/W}$)
 2. $T_A = 25^\circ\text{C}$
 3. $C_L = 2500\text{pF}$

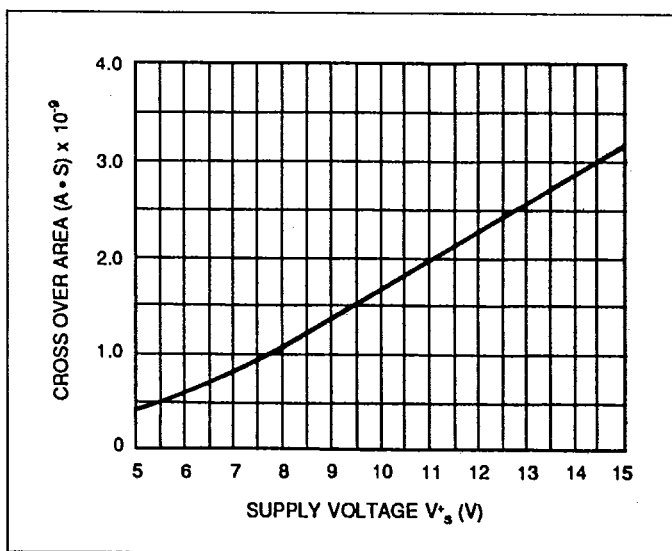
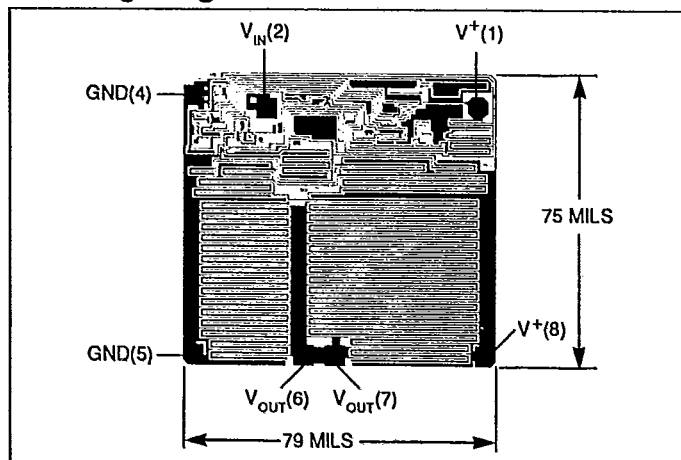


Figure 9. Total nA·S Crossover

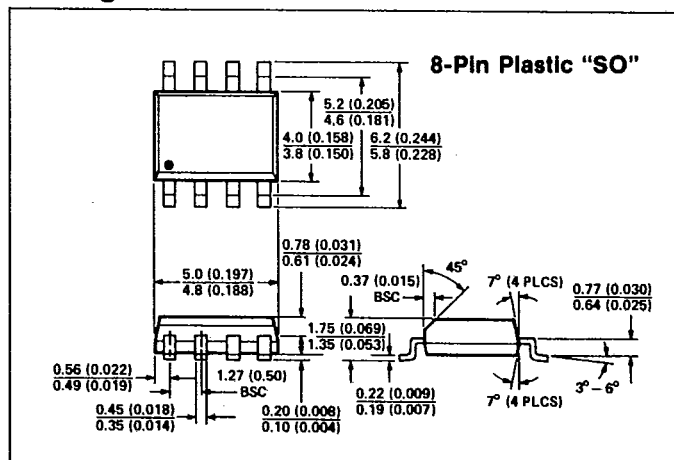
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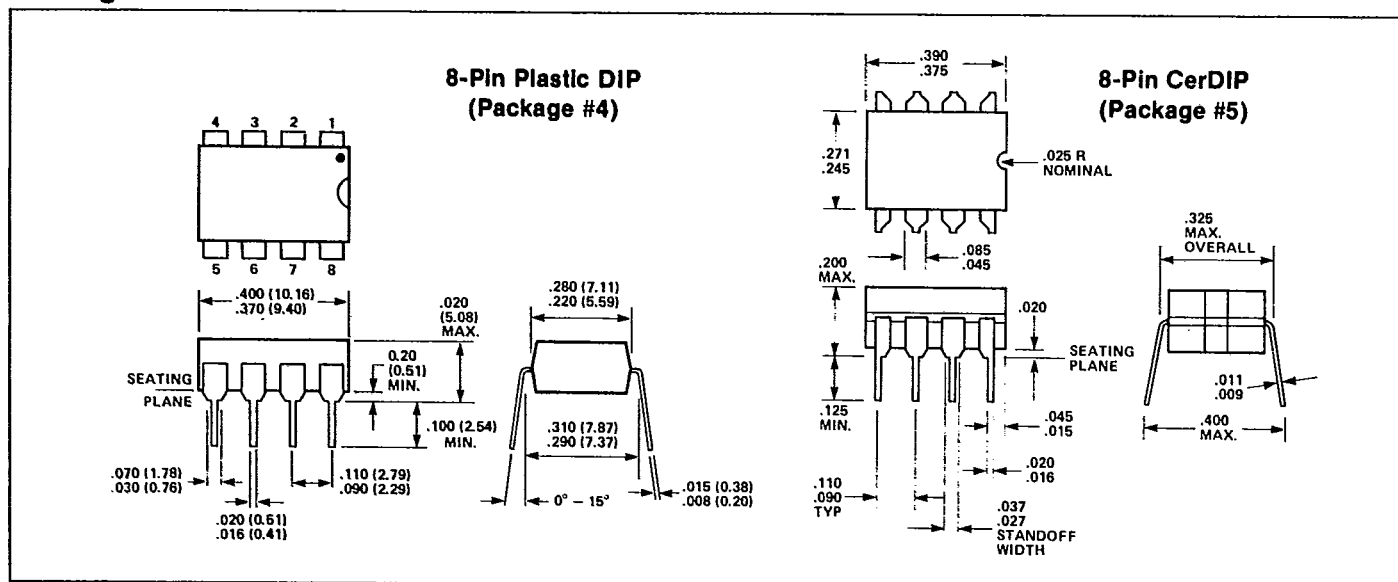
Bonding Diagram



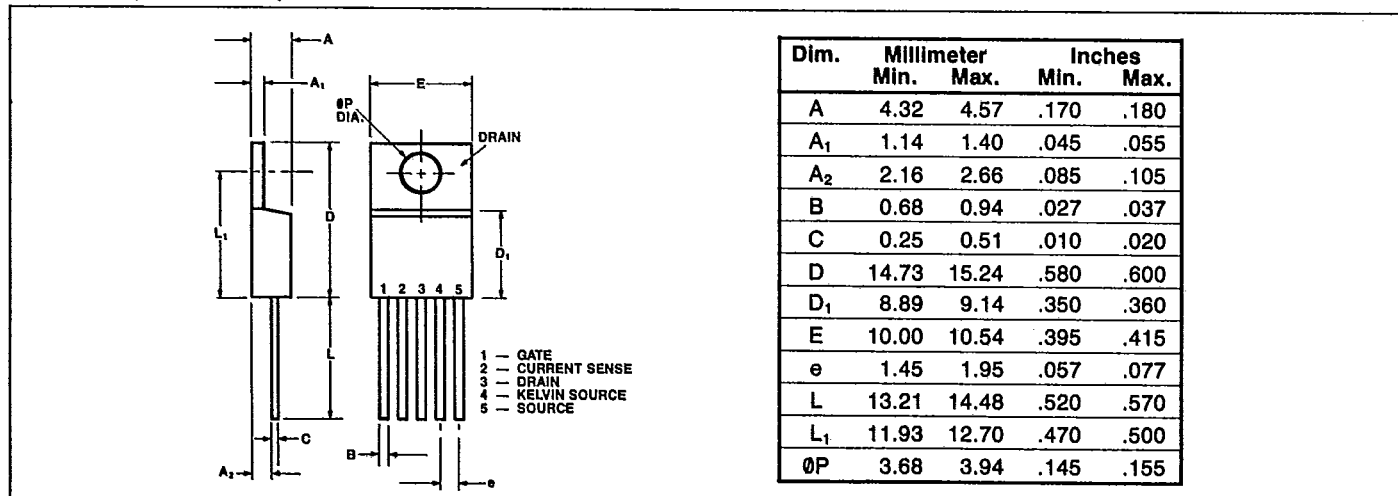
Package Information



Package Information



TO-220 (5 Leaded)



High-Speed, High-Current Single MOSFET/IGBT Driver

IXLD4420/4429

The following families of power drivers are made with a CMOS process to interface between low-level control functions and high-power switching devices, particularly power MOSFETs. The devices are also an optimum choice for capacitive line drivers

where 1.2 A-6 A may be switched. With both inverting and non-inverting inputs available, logic signals of either polarity may be accepted.

Selecting MOSFET Drivers

Device	Drive Current	Output No. & Type	Invert.	Non-Invert	Rated Load (pF)	Rise Time @ Rated Load (nS)	Fall Time @ Rated Load (nS)	Rising Edge Prop. Delay* (nS)	Falling Edge Prop. Delay (nS)	Latch	Input Protected to 5 V Below Gnd RAIL
IXLD1426	1.2 A Peak	dual			1000	30	20	55	80	Resistant	NO
IXLD1427	1.2 A Peak			dual	1000	30	20	55	80	Resistant	NO
IXLD1428	1.2 A Peak	single & single			1000	30	20	55	80	Resistant	NO
IXLD426	1.5 A Peak	dual			1000	30	20	40	75	Resistant	NO
IXLD427	1.5 A Peak			dual	1000	30	20	40	75	Resistant	NO
IXLD428	1.5 A Peak	single & single			1000	30	20	40	75	Resistant	NO
IXLD4426	1.5 A Peak	dual			1000	30	30	40	55	Immune	YES
IXLD4427	1.5 A Peak			dual	1000	30	30	40	55	Immune	YES
IXLD4428	1.5 A Peak	single & single			1000	30	30	40	55	Immune	YES
IXLD4423	3.0 A Peak	dual			1800	20	20	40	40	Immune	YES
IXLD4424	3.0 A Peak			dual	1800	20	20	40	40	Immune	YES
IXLD4425	3.0 A Peak	single & single			1800	20	20	40	40	Immune	YES
IXLD429	6.0 A Peak	single			2500	23	25	53	60	Resistant	NO
IXLD4420	6.0 A Peak			single	2500	25	25	55	55	Immune	YES
IXLD4429	6.0 A Peak	single			2500	25	25	55	55	Immune	YES

MOSFET Die Size vs. Suggested Driver Family

MOSFET Size	Suggested Driver (@ 12 V)	Typical t_r/t_f	Suggested Driver for faster speed (@ 12 V)	Typical t_r/t_f
Size 3	IXLD426/1426/4426	10/26	IXLD4423	7/18
Size 4	IXLD426/1426/4426	26/31	IXLD4420/4429	12/26
Size 5	IXLD426/1426/4426	40/40	IXLD4420/4429	15/15
Size 6	IXLD4420/4429	25/20	—	—
Size 7	IXLD4420/4429	36/35	—	—
Size 8	IXLD4420/4429	50/50	—	—